

Technical Data Sheet



Culver International Ltd

Dynaloy European Manufacturers Agent

Establishing Distributors and Maintaining
The European Network for Dynaloy, Inc.



Engineered Chemistries

ISO 9001:2000

DYNASOLVE 2000

FOR DISSOLVING URETHANE, SILICONES, ANHYDRIDE EPOXIES AND PHOTO RESIST FILMS

Dynasolve 2000 was designed to function as Uresolve Plus SG only with a much higher flash point, low evaporation and elimination of ethylene glycol mono methyl ether. The latter component has health concerns associated with it and this modified version is a much safer product. The Dynasolve 700 series should be tried first as replacement product for Uresolve Plus and Uresolve Plus SG. Should these prove to be too slow or non-functional, then Dynasolve 2000 should be tried for dissolving cured urethane, silicone and anhydride epoxies. Dynasolve 2000 is aluminum safe.

APPLICATIONS:

1. Can be used for the removal of adhesives, polymers, and resins such as epoxies, urethanes, silicones, acrylics and polyesters. It is not, however, typically good at removing silicone-based release agents. To remove silicone release agents from molds, please try Dynasolve CU-9.
2. Can be used for cleaning molds & molding equipment, mixing & metering equipment, laminating & converting equipment, and other equipment having contact with polymers.
3. Excellent for the removal of polymers and other contaminants from electrostatic air filtering cells.
4. Good for paint stripping operations, including many epoxy powder coating systems.
5. Dynasolve 2000 is successful in the removal of polymer-based inks.
6. It has been proven effective in the removal of some parylene materials.

SPECIFICATIONS:

Physical Form	Amber liquid
Specific gravity	1.07
Boiling point	>400°F
Flash point	>200°F (cc)

DIRECTIONS FOR USE:

1. Pour Dynasolve 2000 into a glass or stainless steel container. Keep container covered to avoid evaporative losses. Immerse component in the solvent. Many urethanes will dissolve at room temperature. RTV silicones, silicone molding compounds, anhydride epoxies and cured photo resist films will require heating the solvent to 200°F. It may be necessary to suspend the component in solution so that the material removed will settle to the bottom of the container and not redeposit onto the component.
2. Use of ultrasonic cleaners or mechanical mixing of the solvent will speed up the dissolving rate.
3. After resin has been dissolved, wash Dynasolve 2000 away with water or alcohol.
4. Dynasolve 2000 is hygroscopic and will absorb moisture from the atmosphere. Keep containers closed when not in use.

CAUTION:

Dynasolve 2000 is a reactive solvent, observe proper precautions. Please refer to MSDS before use or disposal.

The information in this sheet is based upon our own research and is considered accurate. However, we make no warranty either expressed or implied regarding accuracy and results to be obtained, because operating conditions of users are beyond our control.

Last Revised By: Lauri Kirby
Last Revision Date: 10/24/00